

**TITLE OF INVENTION: SLURRY COMPOSITION FOR FINAL POLISHING OF
SILICON WAFER FOR REDUCING NUMBER OF SURFACE DEFECTS AND HAZE
AND FINAL POLISHING METHOD USING SAME**

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ABSTRACT

The present invention relates to: a slurry composition for
final polishing of a silicon wafer, which reduces haze and the
number of defects in the surface of an object to be polished
10 and has excellent performance; and a final polishing method
using same, the slurry composition comprising 1-20 wt% of
colloidal silica as abrasive particles, 0.03-0.5 wt% of a
surfactant, 0.1-10 wt% of a pH adjuster, 0.02-2 wt% of a water-
soluble thickener, 0.05-0.2 wt% of a chelating agent, and 0.1-
15 1 wt% of an organic base.

[Fig. 1]